

# Hex Buffer

## MC74LVX50

The MC74LVX50 is an advanced high speed CMOS buffer fabricated with silicon gate CMOS technology.

The internal circuit is composed of three stages, including a buffered output which provides high noise immunity and stable output. The inputs tolerate voltages up to 6.5 V, allowing the interface of 5.0 V systems to 3.0 V systems.

### Features

- High Speed:  $t_{PD} = 4.1 \text{ ns}$  (Typ) at  $V_{CC} = 3.3 \text{ V}$
- Low Power Dissipation:  $I_{CC} = 2 \mu\text{A}$  (Max) at  $T_A = 25^\circ\text{C}$
- High Noise Immunity:  $V_{NIH} = V_{NIL} = 28\% V_{CC}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Designed for 2.0 V to 3.6 V Operating Range
- Low Noise:  $V_{OLP} = 0.5 \text{ V}$  (Max)
- These Devices are Pb-Free and are RoHS Compliant

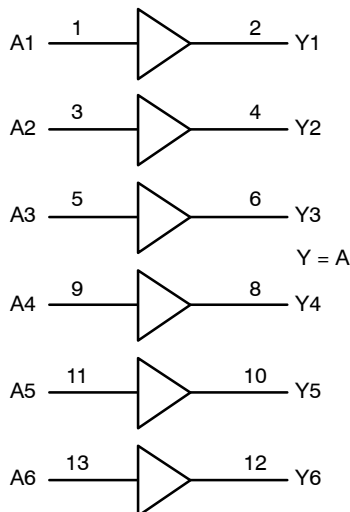


Figure 1. Logic Diagram

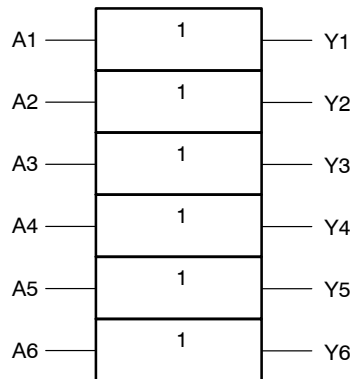


Figure 2. Logic Symbol

### FUNCTION TABLE

| A Input | Y Output |
|---------|----------|
| L       | L        |
| H       | H        |

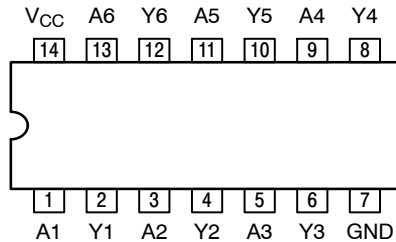


SOIC-14 NB  
D SUFFIX  
CASE 751A



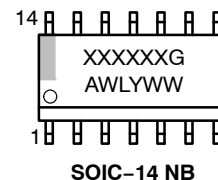
TSSOP-14  
DT SUFFIX  
CASE 948G

### PIN ASSIGNMENT

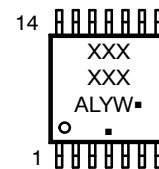


14-Lead (Top View)

### MARKING DIAGRAMS



SOIC-14 NB



TSSOP-14

XXX = Specific Device Code  
A = Assembly Location  
WL, L = Wafer Lot  
Y = Year  
WW, W = Work Week  
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

# MC74LVX50

## MAXIMUM RATINGS

| Symbol               | Parameter                                       | Value                                                                        | Unit       |
|----------------------|-------------------------------------------------|------------------------------------------------------------------------------|------------|
| V <sub>CC</sub>      | DC Supply Voltage                               | − 0.5 to +6.5                                                                | V          |
| V <sub>IN</sub>      | DC Input Voltage                                | − 0.5 to +6.5                                                                | V          |
| V <sub>OUT</sub>     | DC Output Voltage                               | − 0.5 to V <sub>CC</sub> + 0.5                                               | V          |
| I <sub>IK</sub>      | DC Input Diode Current V <sub>I</sub> < GND     | − 20                                                                         | mA         |
| I <sub>OK</sub>      | DC Output Diode Current V <sub>O</sub> < GND    | ±20                                                                          | mA         |
| I <sub>OUT</sub>     | DC Output Sink Current                          | ±25                                                                          | mA         |
| I <sub>CC</sub>      | DC Supply Current per Supply Pin                | ±50                                                                          | mA         |
| T <sub>STG</sub>     | Storage Temperature Range                       | − 65 to + 150                                                                | °C         |
| T <sub>L</sub>       | Lead Temperature, 1 mm from Case for 10 Seconds | 260                                                                          | °C         |
| T <sub>J</sub>       | Junction Temperature under Bias                 | + 150                                                                        | °C         |
| θ <sub>JA</sub>      | Thermal Resistance (Note 1)                     | SOIC<br>TSSOP<br>116<br>150                                                  | °C/W       |
| MSL                  | Moisture Sensitivity                            | Level 1                                                                      |            |
| F <sub>R</sub>       | Flammability Rating Oxygen Index: 30% – 35%     | UL 94–V0 @ 0.125 in                                                          |            |
| V <sub>ESD</sub>     | ESD Withstand Voltage                           | Human Body Model (Note 2)<br>Charged Device Model (Note 3)<br>> 2000<br>2000 | V<br>V     |
| I <sub>Latchup</sub> | Latchup Performance                             | Above V <sub>CC</sub> and Below GND at 85°C (Note 4)                         | ±300<br>mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
2. Tested to EIA/JESD22–A114–A.
3. Tested to JESD22–C101–A.
4. Tested to EIA/JESD78.

## RECOMMENDED OPERATING CONDITIONS

| Symbol          | Parameter                          | Min                            | Max             | Unit |
|-----------------|------------------------------------|--------------------------------|-----------------|------|
| V <sub>CC</sub> | Supply Voltage                     | 2.0                            | 3.6             | V    |
| V <sub>I</sub>  | Input Voltage (Note 5)             | 0                              | 5.5             | V    |
| V <sub>O</sub>  | Output Voltage (HIGH or LOW State) | 0                              | V <sub>CC</sub> | V    |
| T <sub>A</sub>  | Operating Free–Air Temperature     | − 40                           | + 85            | °C   |
| Δt/ΔV           | Input Transition Rise or Fall Rate | V <sub>CC</sub> = 3.0 V ±0.3 V |                 | ns/V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

5. Unused inputs may not be left open. All inputs must be tied to a high– or low–logic input voltage level.

NOTE: The θ<sub>JA</sub> of the package is equal to 1/Derating. Higher junction temperatures may affect the expected lifetime of the device per the table and figure below.

# MC74LVX50

## DC ELECTRICAL CHARACTERISTICS

| Symbol          | Parameter                                                                            | Test Conditions                                                                 | V <sub>CC</sub><br>(V) | T <sub>A</sub> = 25°C |            |                    | T <sub>A</sub> ≤ 85°C |                    | Unit |
|-----------------|--------------------------------------------------------------------------------------|---------------------------------------------------------------------------------|------------------------|-----------------------|------------|--------------------|-----------------------|--------------------|------|
|                 |                                                                                      |                                                                                 |                        | Min                   | Typ        | Max                | Min                   | Max                |      |
| V <sub>IH</sub> | High-Level Input Voltage                                                             |                                                                                 | 2.0<br>3.0<br>3.6      | 1.5<br>2.0<br>2.4     |            |                    | 1.5<br>2.0<br>2.4     |                    | V    |
| V <sub>IL</sub> | Low-Level Input Voltage                                                              |                                                                                 | 2.0<br>3.0<br>3.6      |                       |            | 0.5<br>0.8<br>0.8  |                       | 0.5<br>0.8<br>0.8  | V    |
| V <sub>OH</sub> | High-Level Output Voltage<br>(V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ) | I <sub>OH</sub> = -50 μA<br>I <sub>OH</sub> = -50 μA<br>I <sub>OH</sub> = -4 mA | 2.0<br>3.0<br>3.0      | 1.9<br>2.9<br>2.58    | 2.0<br>3.0 |                    | 1.9<br>2.9<br>2.48    |                    | V    |
| V <sub>OL</sub> | Low-Level Output Voltage<br>(V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> )  | I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 50 μA<br>I <sub>OL</sub> = 4 mA    | 2.0<br>3.0<br>3.0      |                       | 0.0<br>0.0 | 0.1<br>0.1<br>0.36 |                       | 0.1<br>0.1<br>0.44 | V    |
| I <sub>IN</sub> | Input Leakage Current                                                                | V <sub>IN</sub> = 5.5 V or GND                                                  | 0 to<br>3.6            |                       |            | ±0.1               |                       | ±1.0               | μA   |
| I <sub>CC</sub> | Quiescent Supply Current                                                             | V <sub>IN</sub> = V <sub>CC</sub> or GND                                        | 3.6                    |                       |            | 2.0                |                       | 20.0               | μA   |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## AC ELECTRICAL CHARACTERISTICS Input t<sub>r</sub> = t<sub>f</sub> = 3.0 ns

| Symbol                                 | Parameter                              | Test Conditions                                                                       | T <sub>A</sub> = 25°C |            |              | T <sub>A</sub> ≤ 85°C |              | Unit |
|----------------------------------------|----------------------------------------|---------------------------------------------------------------------------------------|-----------------------|------------|--------------|-----------------------|--------------|------|
|                                        |                                        |                                                                                       | Min                   | Typ        | Max          | Min                   | Max          |      |
| t <sub>PLH</sub> ,<br>t <sub>PHL</sub> | Propagation Delay,<br>Input A to Y     | V <sub>CC</sub> = 2.7 V      C <sub>L</sub> = 15 pF<br>C <sub>L</sub> = 50 pF         |                       | 5.4<br>7.9 | 10.1<br>13.6 | 1.0<br>1.0            | 12.5<br>16.0 | ns   |
|                                        |                                        | V <sub>CC</sub> = 3.3 V ± 0.3 V      C <sub>L</sub> = 15 pF<br>C <sub>L</sub> = 50 pF |                       | 4.1<br>6.6 | 6.2<br>9.7   | 1.0<br>1.0            | 7.5<br>11.5  |      |
| t <sub>OSHL</sub><br>t <sub>OSLH</sub> | Output-to-Output Skew<br>(Note 6)      | V <sub>CC</sub> = 2.7 V      C <sub>L</sub> = 50 pF                                   |                       |            | 1.5          |                       | 1.5          | ns   |
|                                        |                                        | V <sub>CC</sub> = 3.3 V ±0.3V      C <sub>L</sub> = 50 pF                             |                       |            | 1.5          |                       | 1.5          |      |
| C <sub>IN</sub>                        | Input Capacitance                      |                                                                                       |                       | 4          | 10           |                       | 10           | pF   |
| C <sub>PD</sub>                        | Power Dissipation Capacitance (Note 7) | Typical @ 25°C, V <sub>CC</sub> = 3.3 V                                               |                       |            |              |                       |              | pF   |
|                                        |                                        | 15                                                                                    |                       |            |              |                       |              |      |

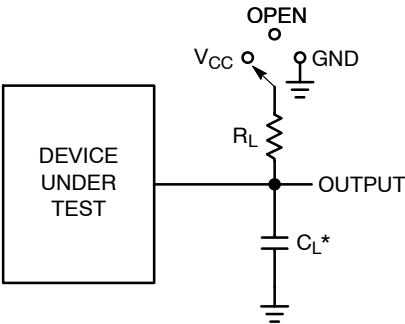
6. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

7. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

## NOISE CHARACTERISTICS Input t<sub>r</sub> = t<sub>f</sub> = 3.0ns, C<sub>L</sub> = 50pF, V<sub>CC</sub> = 3.3 V

| Symbol           | Characteristic                               | T <sub>A</sub> = 25°C |      | Unit |
|------------------|----------------------------------------------|-----------------------|------|------|
|                  |                                              | Typ                   | Max  |      |
| V <sub>OLP</sub> | Quiet Output Maximum Dynamic V <sub>OL</sub> | 0.3                   | 0.5  | V    |
| V <sub>OLV</sub> | Quiet Output Minimum Dynamic V <sub>OL</sub> | -0.3                  | -0.5 | V    |
| V <sub>IHD</sub> | Minimum High Level Dynamic Input Voltage     |                       | 2.0  | V    |
| V <sub>ILD</sub> | Maximum Low Level Dynamic Input Voltage      |                       | 0.8  | V    |

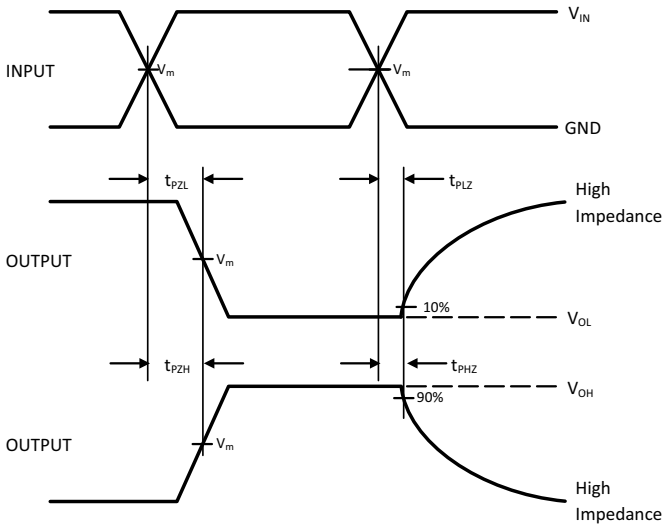
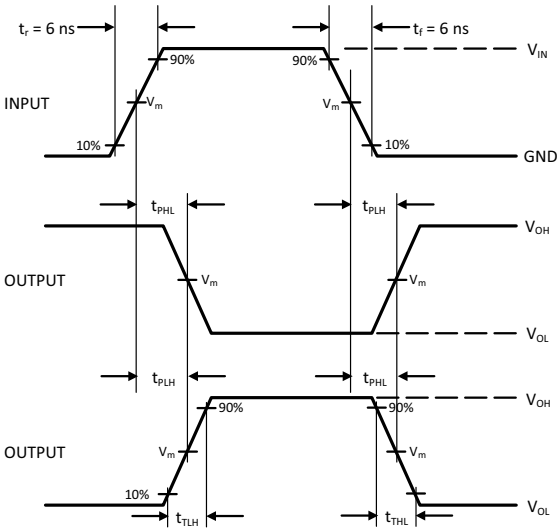
MC74LVX50



\*C<sub>L</sub> Includes probe and jig capacitance

| Test                                | Switch Position | C <sub>L</sub>               | R <sub>L</sub> |
|-------------------------------------|-----------------|------------------------------|----------------|
| t <sub>PLH</sub> / t <sub>PHL</sub> | Open            | See AC Characteristics Table | 1 kΩ           |
| t <sub>PLZ</sub> / t <sub>PZL</sub> | V <sub>CC</sub> |                              |                |
| t <sub>PHZ</sub> / t <sub>PZH</sub> | GND             |                              |                |

Figure 3. Test Circuit



| Device    | V <sub>IN</sub> , V | V <sub>m</sub> , V    |
|-----------|---------------------|-----------------------|
| MC74LVX50 | V <sub>CC</sub>     | 50% x V <sub>CC</sub> |

Figure 4. Switching Waveforms

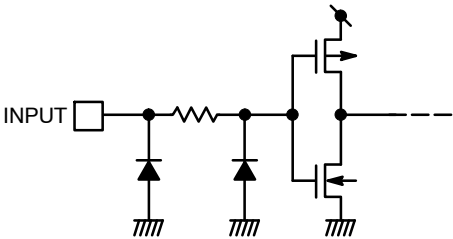


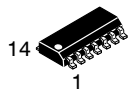
Figure 5. Input Equivalent Circuit

## MC74LVX50

### ORDERING INFORMATION

| Device         | Marking   | Package  | Shipping <sup>†</sup> |
|----------------|-----------|----------|-----------------------|
| MC74LVX50DR2G  | LVX50     | SOIC-14  | 2500 Tape & Reel      |
| MC74LVX50DTG   | LVX<br>50 | TSSOP-14 | 96 Units / Rail       |
| MC74LVX50DTR2G | LVX<br>50 | TSSOP-14 | 2500 Tape & Reel      |

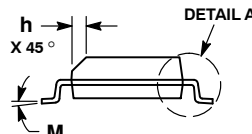
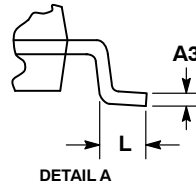
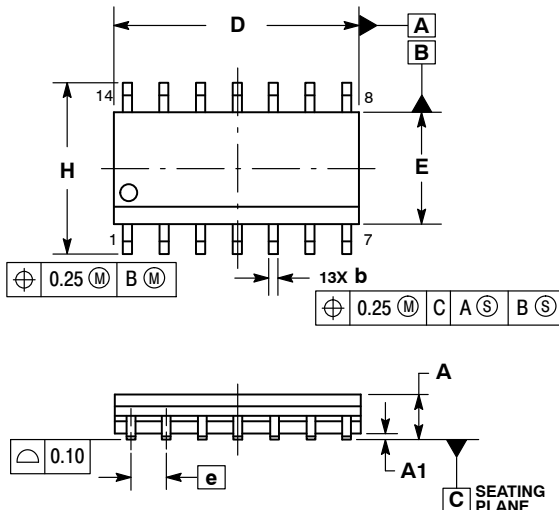
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



SCALE 1:1

SOIC-14 NB  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

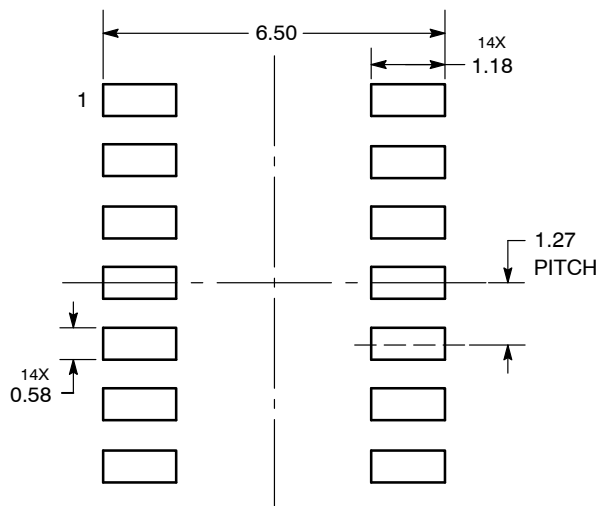


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 1.35        | 1.75 | 0.054     | 0.068 |
| A1  | 0.10        | 0.25 | 0.004     | 0.010 |
| A3  | 0.19        | 0.25 | 0.008     | 0.010 |
| b   | 0.35        | 0.49 | 0.014     | 0.019 |
| D   | 8.55        | 8.75 | 0.337     | 0.344 |
| E   | 3.80        | 4.00 | 0.150     | 0.157 |
| e   | 1.27 BSC    |      | 0.050 BSC |       |
| H   | 5.80        | 6.20 | 0.228     | 0.244 |
| h   | 0.25        | 0.50 | 0.010     | 0.019 |
| L   | 0.40        | 1.25 | 0.016     | 0.049 |
| M   | 0°          | 7°   | 0°        | 7°    |

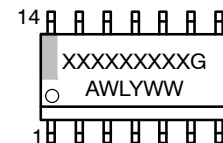
SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC  
MARKING DIAGRAM\*



XXXXXX = Specific Device Code  
A = Assembly Location  
WL = Wafer Lot  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

|                  |             |                                                                                                                                                                                     |
|------------------|-------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| DOCUMENT NUMBER: | 98ASB42565B | Electronic versions are uncontrolled except when accessed directly from the Document Repository.<br>Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION:     | SOIC-14 NB  | PAGE 1 OF 2                                                                                                                                                                         |

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

SOIC-14  
CASE 751A-03  
ISSUE L

DATE 03 FEB 2016

STYLE 1:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. NO CONNECTION  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

STYLE 2:  
CANCELLED

STYLE 3:  
PIN 1. NO CONNECTION  
2. ANODE  
3. ANODE  
4. NO CONNECTION  
5. ANODE  
6. NO CONNECTION  
7. ANODE  
8. ANODE  
9. ANODE  
10. NO CONNECTION  
11. ANODE  
12. ANODE  
13. NO CONNECTION  
14. COMMON CATHODE

STYLE 4:  
PIN 1. NO CONNECTION  
2. CATHODE  
3. CATHODE  
4. NO CONNECTION  
5. CATHODE  
6. NO CONNECTION  
7. CATHODE  
8. CATHODE  
9. CATHODE  
10. NO CONNECTION  
11. CATHODE  
12. CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

STYLE 5:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. NO CONNECTION  
7. COMMON ANODE  
8. COMMON CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. ANODE/CATHODE  
12. ANODE/CATHODE  
13. NO CONNECTION  
14. COMMON ANODE

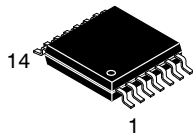
STYLE 6:  
PIN 1. CATHODE  
2. CATHODE  
3. CATHODE  
4. CATHODE  
5. CATHODE  
6. CATHODE  
7. CATHODE  
8. ANODE  
9. ANODE  
10. ANODE  
11. ANODE  
12. ANODE  
13. ANODE  
14. ANODE

STYLE 7:  
PIN 1. ANODE/CATHODE  
2. COMMON ANODE  
3. COMMON CATHODE  
4. ANODE/CATHODE  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. ANODE/CATHODE  
8. ANODE/CATHODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. COMMON CATHODE  
12. COMMON ANODE  
13. ANODE/CATHODE  
14. ANODE/CATHODE

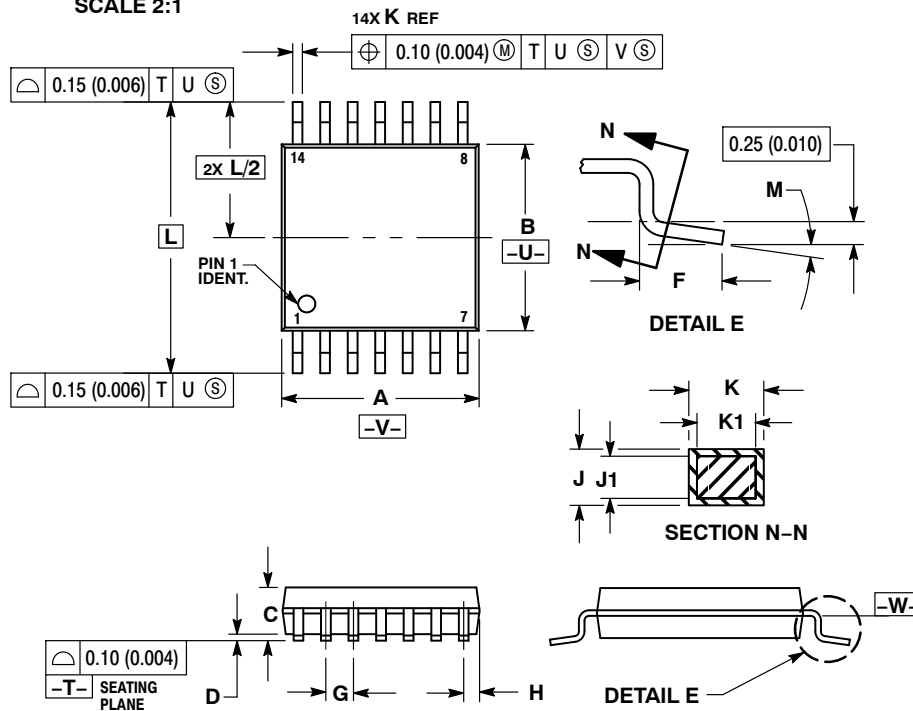
STYLE 8:  
PIN 1. COMMON CATHODE  
2. ANODE/CATHODE  
3. ANODE/CATHODE  
4. NO CONNECTION  
5. ANODE/CATHODE  
6. ANODE/CATHODE  
7. COMMON ANODE  
8. COMMON ANODE  
9. ANODE/CATHODE  
10. ANODE/CATHODE  
11. NO CONNECTION  
12. ANODE/CATHODE  
13. ANODE/CATHODE  
14. COMMON CATHODE

|                  |             |                                                                                                                                                                                     |
|------------------|-------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| DOCUMENT NUMBER: | 98ASB42565B | Electronic versions are uncontrolled except when accessed directly from the Document Repository.<br>Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION:     | SOIC-14 NB  | PAGE 2 OF 2                                                                                                                                                                         |

**onsemi** and **onsemi** are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

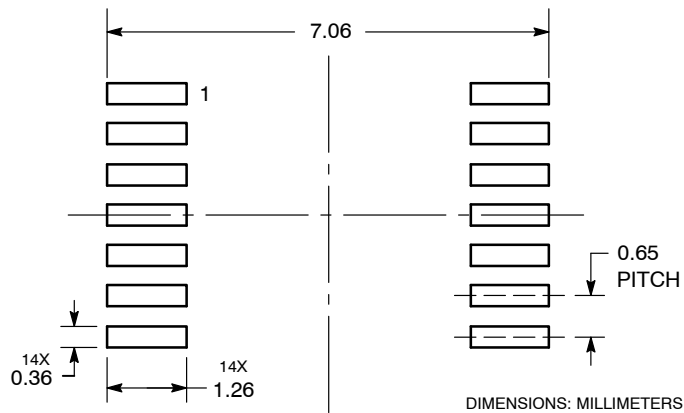

**TSSOP-14 WB**  
**CASE 948G**  
**ISSUE C**

DATE 17 FEB 2016

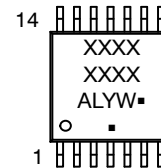

**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 4.90        | 5.10 | 0.193     | 0.200 |
| B   | 4.30        | 4.50 | 0.169     | 0.177 |
| C   | ---         | 1.20 | ---       | 0.047 |
| D   | 0.05        | 0.15 | 0.002     | 0.006 |
| F   | 0.50        | 0.75 | 0.020     | 0.030 |
| G   | 0.65 BSC    |      | 0.026 BSC |       |
| H   | 0.50        | 0.60 | 0.020     | 0.024 |
| J   | 0.09        | 0.20 | 0.004     | 0.008 |
| J1  | 0.09        | 0.16 | 0.004     | 0.006 |
| K   | 0.19        | 0.30 | 0.007     | 0.012 |
| K1  | 0.19        | 0.25 | 0.007     | 0.010 |
| L   | 6.40 BSC    |      | 0.252 BSC |       |
| M   | 0°          | 8°   | 0°        | 8°    |

**RECOMMENDED  
SOLDERING FOOTPRINT\***


\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC  
MARKING DIAGRAM\***


A = Assembly Location  
L = Wafer Lot  
Y = Year  
W = Work Week  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

|                         |                    |                                                                                                                                                                                  |
|-------------------------|--------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>DOCUMENT NUMBER:</b> | <b>98ASH70246A</b> | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| <b>DESCRIPTION:</b>     | <b>TSSOP-14 WB</b> | <b>PAGE 1 OF 1</b>                                                                                                                                                               |

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.



**onsemi**, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## ADDITIONAL INFORMATION

### TECHNICAL PUBLICATIONS:

Technical Library: [www.onsemi.com/design/resources/technical-documentation](http://www.onsemi.com/design/resources/technical-documentation)  
onsemi Website: [www.onsemi.com](http://www.onsemi.com)

### ONLINE SUPPORT: [www.onsemi.com/support](http://www.onsemi.com/support)

For additional information, please contact your local Sales Representative at  
[www.onsemi.com/support/sales](http://www.onsemi.com/support/sales)